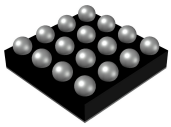
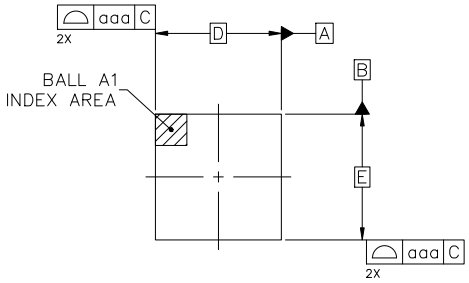
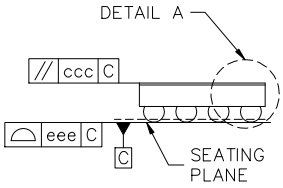


WLCSP16 1.56x1.56x0.29, 0.40P
CASE 567UX
ISSUE A

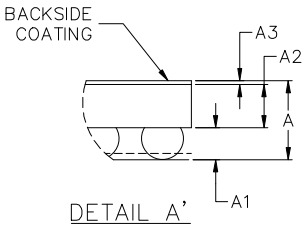
DATE 31 MAY 2024



TOP VIEW



SIDE VIEW

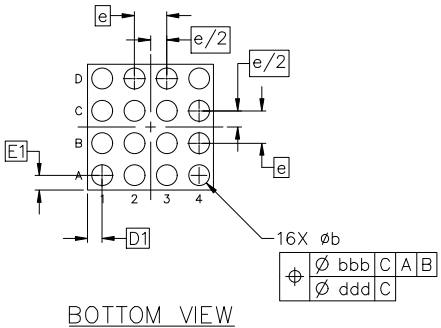


DETAIL A'
SCALE 2:1

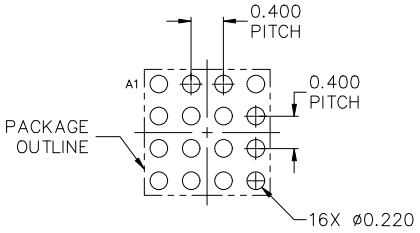
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M−2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.452	0.490	0.528
A1	0.178	0.198	0.218
A2	0.252	0.267	0.282
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	1.560 BSC		
D1	0.180 BSC		
E	1.560 BSC		
E1	0.180 BSC		
e	0.400 BSC		
TOLERANCES OF FORM AND POSITION			
aaa	0.030		
bbb	0.050		
ccc	0.050		
ddd	0.030		
eee	0.050		



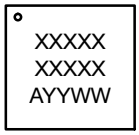
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**WLCSP16 1.56x1.56x0.29, 0.40P**	**PAGE 1 OF 1**